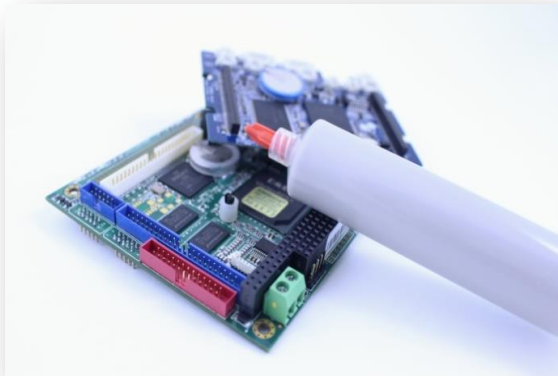


TG-NSP25

Non-Silicone Thermal Putty



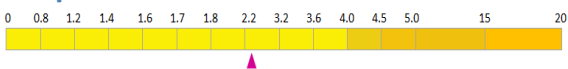
Features

- Silicone free thermal gel
- Shapeable and compressible
- Low thermal resistance
- No fluidity
- Best for north bridge IC

Applications

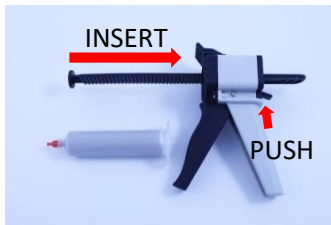
- Electronic components: IC, CPU, MOS, LED,
- Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook,
- PC, Telecom Device, Wireless Hub,
- DDR II Module, DVD Applications, Hand-set Applications etc.

Properties



Thermal Conductivity: 2.5 W/m.K

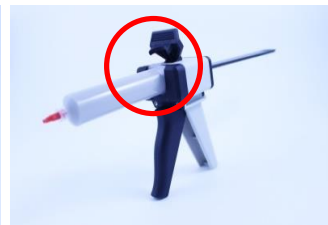
Operation Manual - Gel Gun



STEP1-Push the latch



STEP 2-Put the tube in



STEP3-Close the cover



STEP4-Take off the plug

Reliability

Thermal Impedance	Initial	200Hr	400Hr	700Hr	1000Hr
125°C Aging	0.052	0.053	0.052	0.053	0.054
85°C/85% RH	0.052	0.051	0.050	0.051	0.052

Physical Properties	TG-NSP25	Unit	Tolerance	Test Method
Thermal Conductivity	2.5	W / mK	±0.25	ASTM D5470
Color	Gray	-	-	Visual
Solid Content	100	%	-	-
Viscosity 0.5rpm	5000	Pa·s	-	Brookfield
Density	2.6	g / cm ³	-	ASTM D792
Low MW Siloxane (D3-10)	0	ppm	-	GC/MS
Volume Resistivity	10 ¹⁴	Ohm-m	-	ASTM D257
Working Temp.	-50~+150	°C	-	-
Standard package	78g/ 143g/ 1KG	Tube/Pot	-	-

Need Samples?

TG-NSP25 — 50gram
1 2

1. Choose the P/N
2. Fill the quantity you need

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Thermal Interface Materials: Thermal Pad, Thermal Tape, Thermal Grease, Ceramic Heat Spreader

